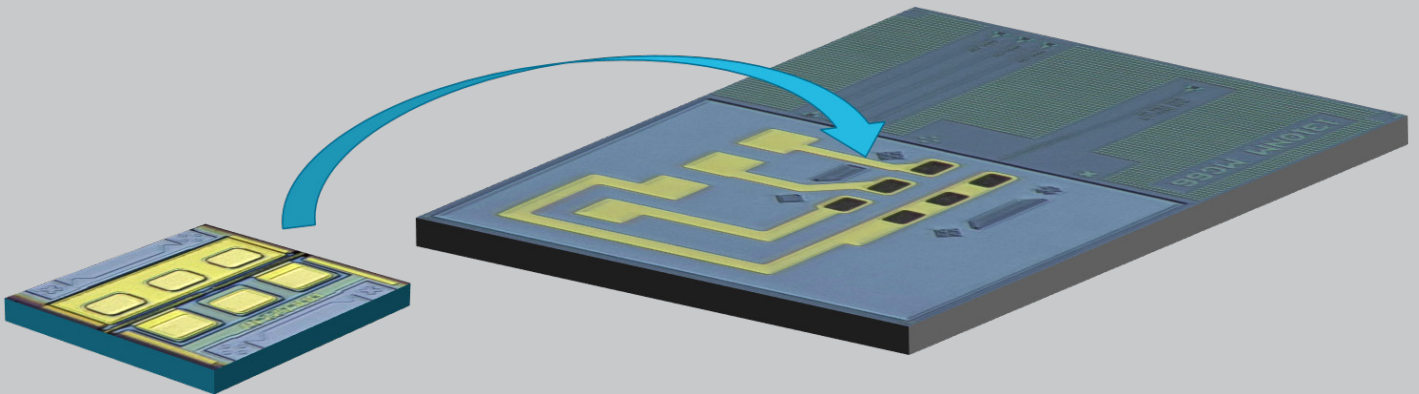


# INP-TRANSMITTER CHIPS FOR HYBRID INTEGRATION



## AT A GLANCE

InP light sources for application in photonic multi-chip approaches

### Features

- flip-chip configuration
- horizontal and vertical integration (2D and 3D)
- integrated taper for low optical coupling loss & relaxed alignment tolerance
- lateral & vertical positioning
- etched facets on request
- flexible adaption of devices corresponding to customer's photonic platforms

### Application

- Telecom/Datacom
- Sensors

### Photonic platforms

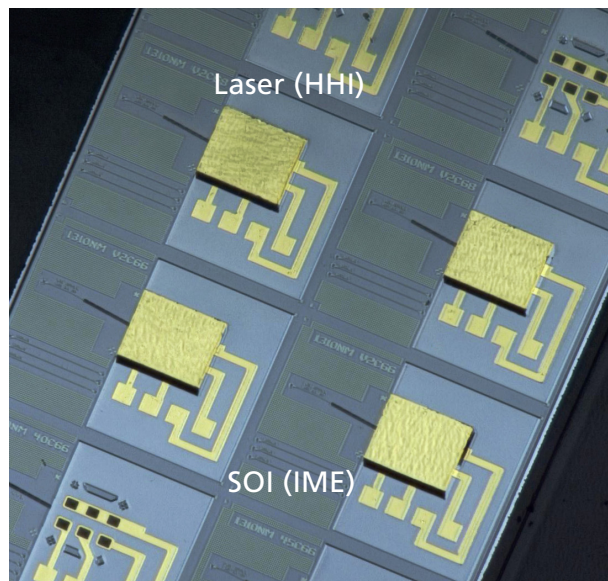
- Silicon on Insulator (SOI)
- Silicon-Nitride (SiN)
- Lithium Niobate-On-Insulator (LNOI)
- Glass
- Polymer

### Functionality

- high power DFB-lasers
- high power gain chips
- high speed gain chips
- semiconductor optical amplifiers (SOAs)

### Configuration

- horizontal and vertical emitters
- single chips and array



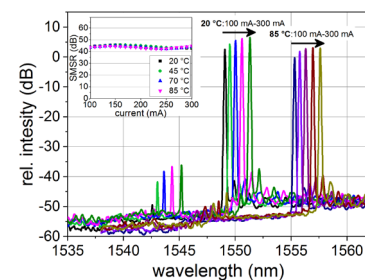
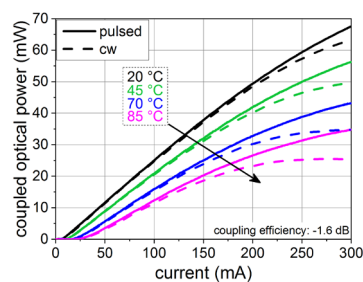
Example: Tolerant low-loss-butt-joint coupling of InP chip to SOI-waveguide

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Power coupled to SiN-waveguide and optical spectra for flip-chip integrated DFB laser